

The logo for "Scaling at the Edge". It features a stylized white cloud on the left containing a circuit board icon with a blue arrow pointing upwards and to the right. To the right of the cloud, the words "SCALING AT THE" are stacked above "EDGE" in a bold, italicized, white sans-serif font.

Lanner's
Scalable EDGE
Cloud Platform

Lanner

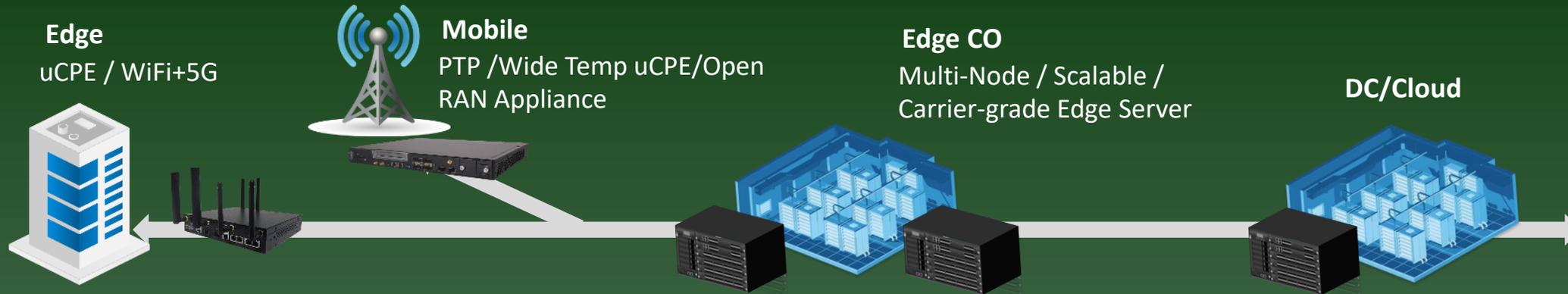


Sven Freudenfeld

CTO, Telecom Applications BU, Lanner

Lanner's Solutions for Edge Network

Lanner



LTE+5G/ uCPE



LTE+5G /Wide Temp uCPE

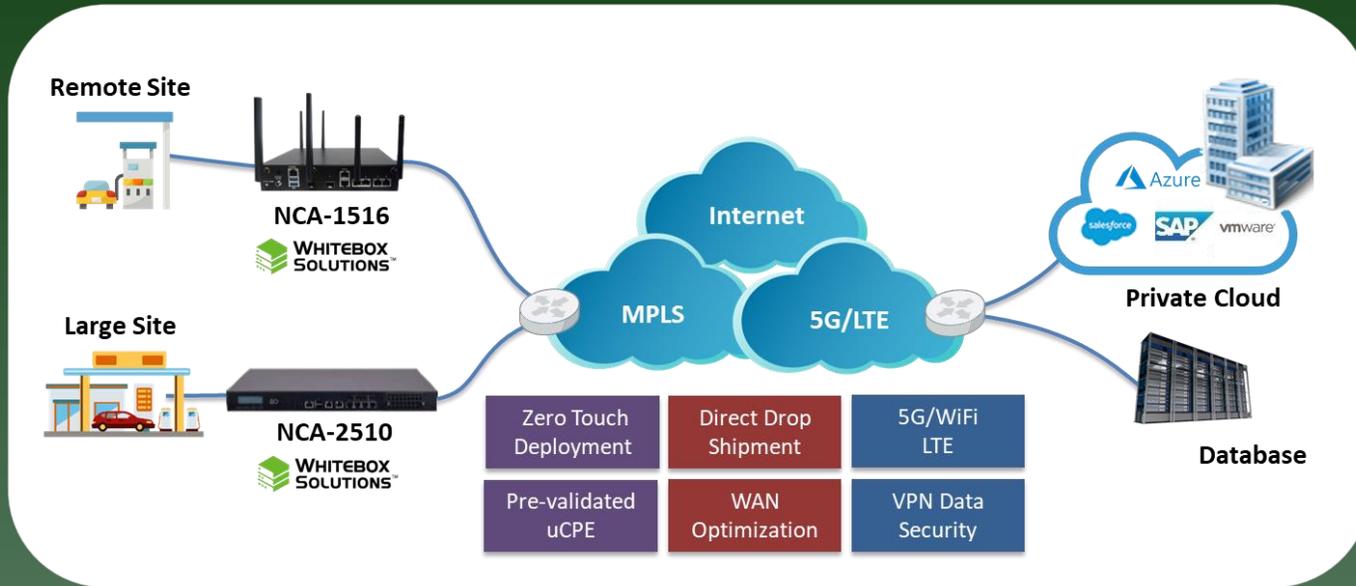


Multi-Node / Scalable / Carrier-grade edge server



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Whitebox uCPE for SD-WAN



uCPE/vCPE Platform

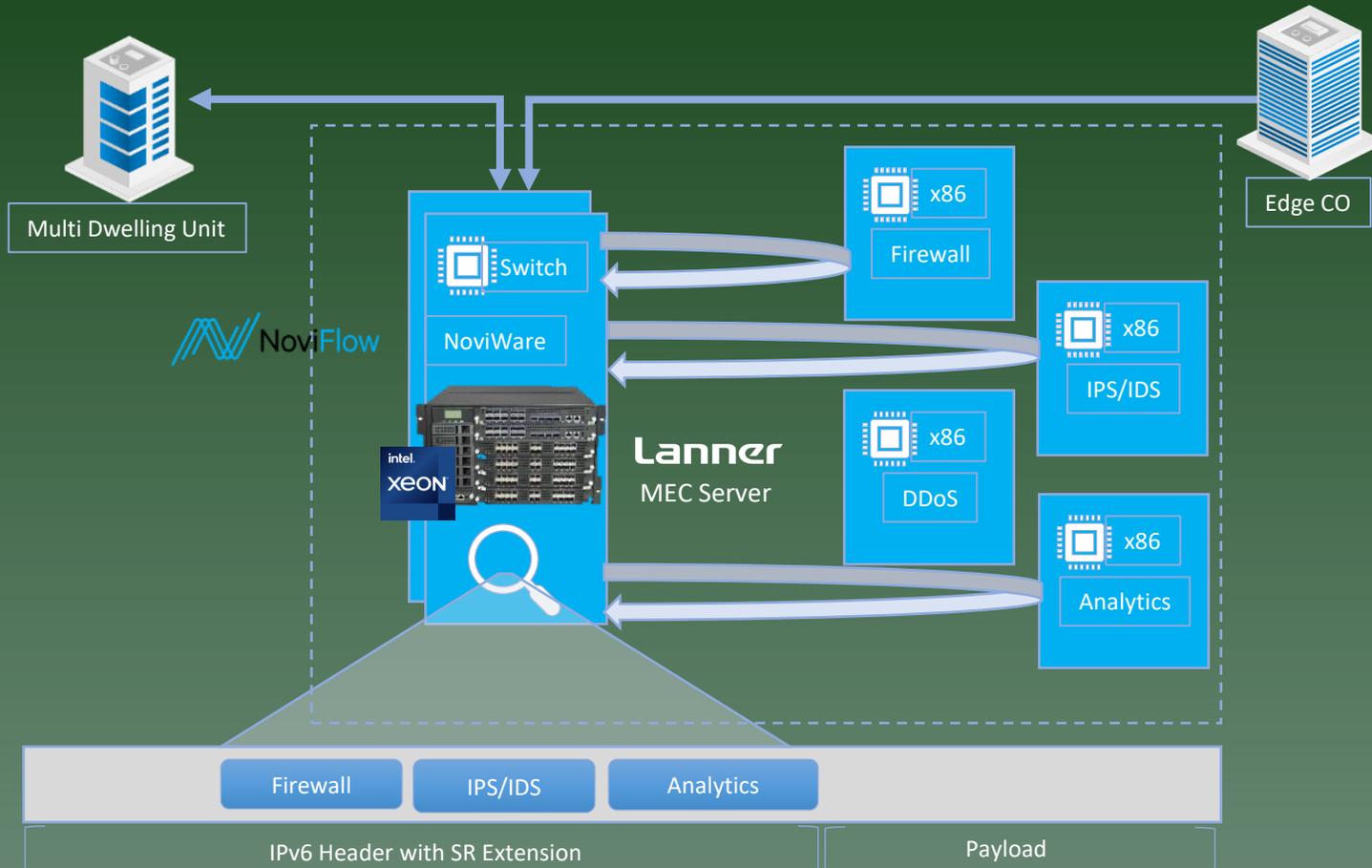
- uCPE Pre-validated by 30 partners to accelerate SDN/NFV time-to-market deployment for SI and TEM
- Deployed in enterprises, retail chains, and distributed branches for more than 200,000 devices.

	<h3>NCA-1513</h3>	<h3>NCA-1516</h3>	<h3>NCA-4025</h3>	<h3>NCA-5710</h3>
	<p>4~16C Intel Atom® Processor 4x GbE RJ45 + 2x SFP</p>	<p>4~16C Intel Atom® Processor 6x GbE RJ45 + 2x SFP+</p>	<p>8~16C Intel® Xeon® D Processor 8x GbE RJ45 + 4x SFP+</p>	<p>16~56C Intel® Xeon® Processor 4x NIC / Dual PSU</p>

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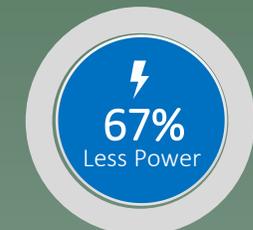
MEC Server for SRv6 Service Chaining

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Enabling edge services

- Reduce Cost, implemented on white box hardware, no need for dedicated appliances
- Flexible deployment model, allows Carriers to put services closer to the customer (micro) or chain across the network (macro)
- Density, host multiple revenue generating services in a single box

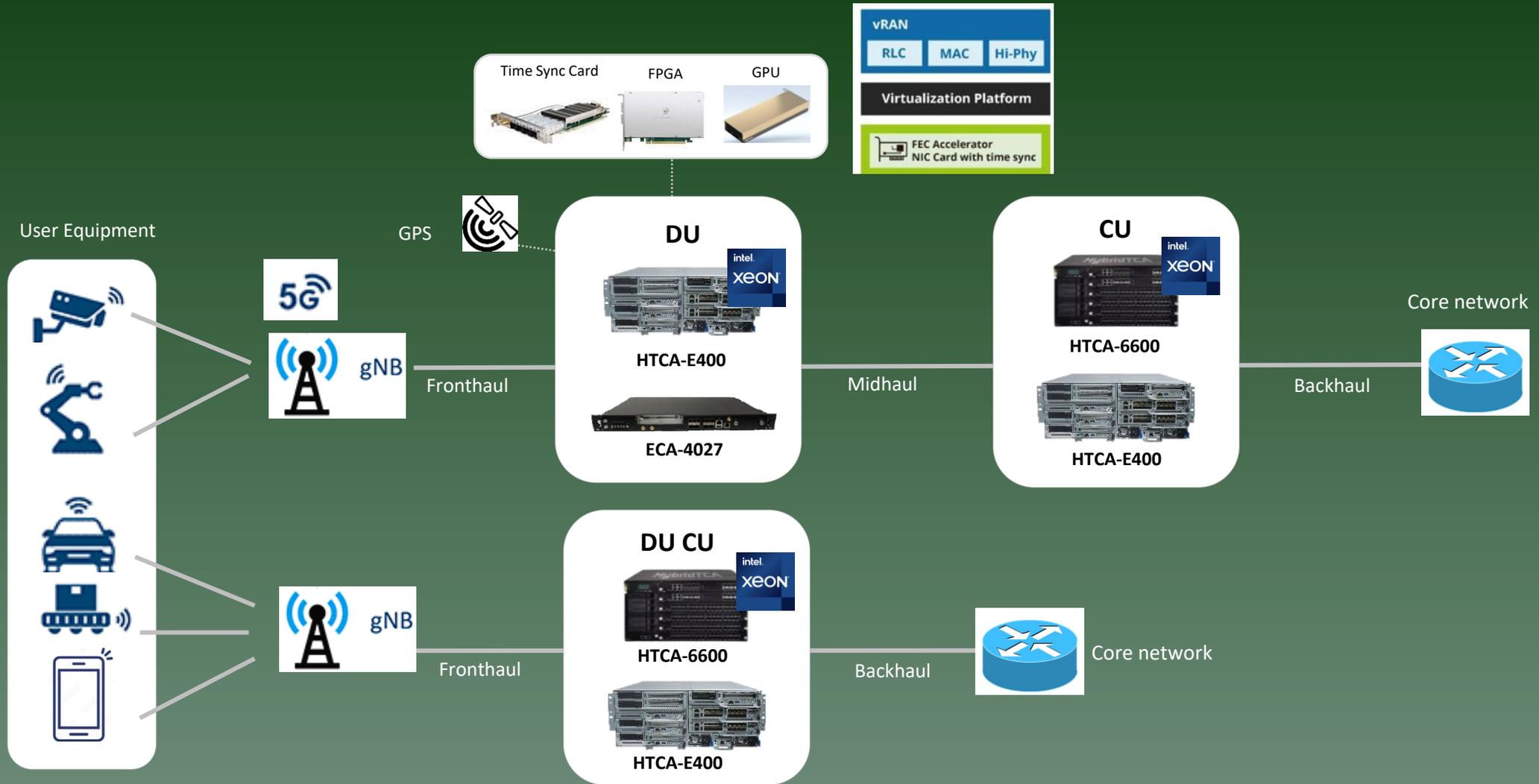


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Estimated comparison to purpose build traditional NEP's vendors

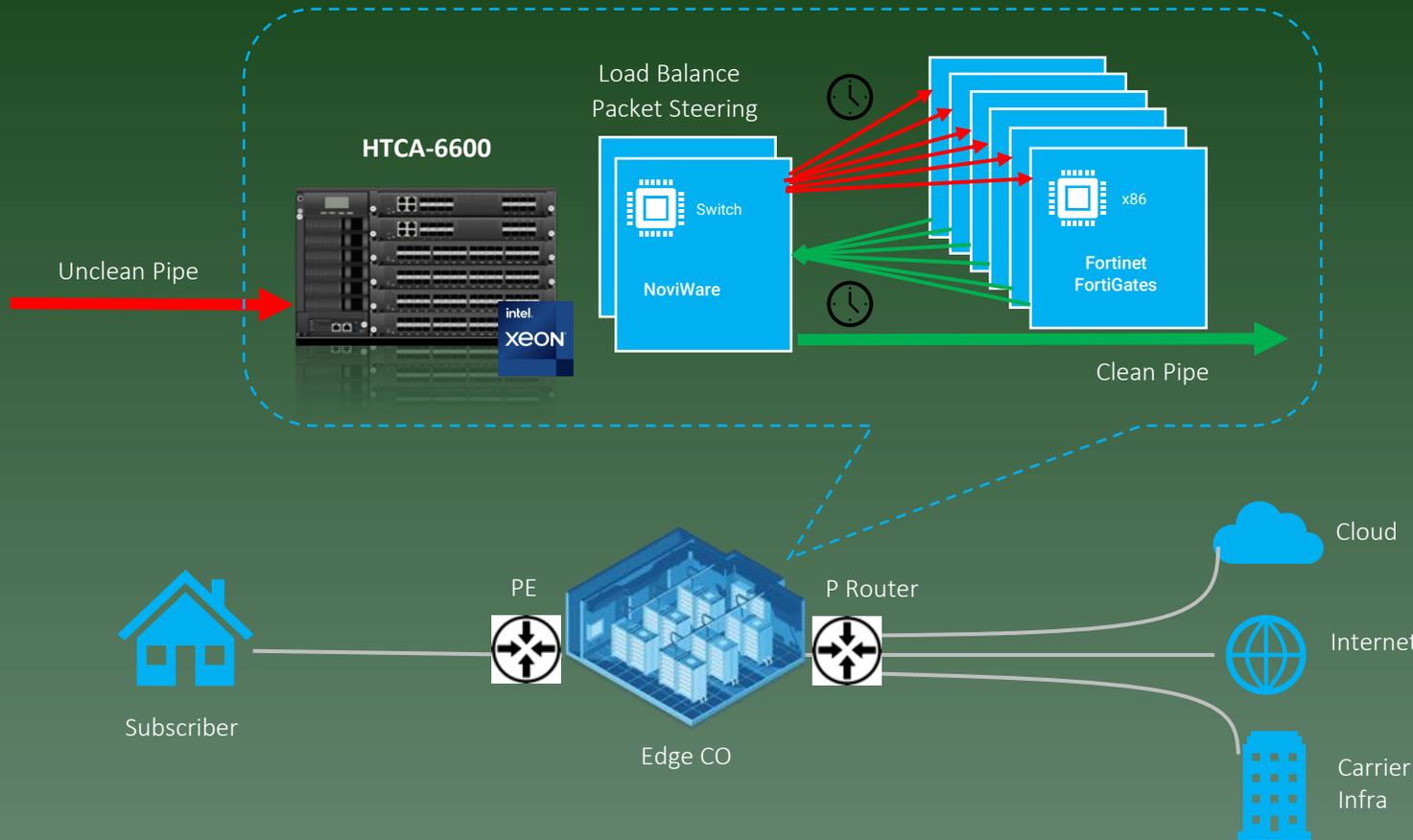
Open RAN Appliance for DU/CU



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Edge Server for Scalable Security Perimeter

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Scalable edge services

- Scale security tools using load balancing, packet filtering, packet steering and service chaining
- Measure latency of security tools using INT for SLA compliance
- Simplify virtual appliance deployment with a network infrastructure designed for security tools:
 - Ex. DDoS, CGNAT, Firewalls and IDS/IPS

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Carrier-grade MEC Server HTCA-6600

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More info:



Multiple Computing Blades
Multicore computing capability with dual 2nd Gen Intel® Xeon® Scalable Processor for each blade



P4 Switching Capacity
● Packet load balancing
● Blade communications



Fully Modular Design
A wide range of networking blades available

Control Panel



Storage
SATA HDD bay for each MB blade

High Availability
● Hot plug & hot-swap
● Redundant PSU & fans
● Rich IPMI manageability

Middle Plane



HTCA (Hybrid Telecommunications Computing Architecture)

- 2U to 6U appliance
- Integration of control plane and data plane
- High-speed switching with 3.2Tbps throughput
- NEBS ready
- High availability design

Computing Blades
2x 2nd Generation Intel® Xeon® Scalable Processors
Max. 512GB Memory



Network I/O Blades
10G SFP+, 40G QSFP+
100G QSFP28



Switch Blade
Intel® Tofino™ and
Broadcom Tomahawk



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Carrier-grade MEC Server HTCA-E400

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More info:



Short-depth 450mm chassis and front I/O design



HTCA – E400 Edge Compute

- ◎ 4U short chassis appliance
- ◎ Integration of control plane and data plane
- ◎ High-speed P4 switching
- ◎ NEBS level 3 compatible design, edge solution

5 x 3rd Gen Intel® Xeon® Scalable Processor

PCIe Expansion for GPU and FPGA Card

Intel® Tofino™ P4 switch ASICs

IEEE 1588 PTP v2 Time Sync

OCP NIC 3.0 Module Compatible

Chassis Management

1U Compute Sled

3rd Gen Intel® Xeon® Scalable Processor FHHL PCIe by 16 OCP NIC 3.0



2U Compute Sled

3rd Gen Intel® Xeon® Scalable Processor PCIE FH3/4L Double Width OCP NIC 3.0



Switch Sled

6x 100G, 8x 10/25G SFP+ Optional IEEE 1588



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Lanner Network Appliance for
5G Edge Cloud:



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